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Product Change Notification - JAON-30ZGKM586 [\(Printer Friendly\)](#)

Date: 05 Nov 2015
Notification subject: CCB 1754 Final Notice: Qualification of 8390A die attach material for products available 14L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site.

Notification text: **PCN Status:** Final notification
Microchip Parts Affected: Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.
 NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).
Description of Change: Qualification of 8390A die attach material for products available 14L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site.

Pre Change: 3280 die attach material
Post Change: 3280 die attach material or 8390A die attach material

Impacts to Data Sheet: None

Reason for Change: To improve on-time delivery performance by qualifying 8390A die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: November 15, 2015 (date code: 1546)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

	November 2015	December 2015
Qual Report Availability	X	
Final PCN Issue Date	X	
Implementation Date	X	

Markings to Distinguish Revised from Unrevised Devices: Traceability code

Revision History: **November 5, 2015:** Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-30ZGKM586_Qual_Report.pdf](#)
[PCN_JAON-30ZGKM586_Affected_CPN.pdf](#)
[PCN_JAON-30ZGKM586_Affected_CPN.xls](#)

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